

L Number	Hits	Search Text	DB	Time stamp
1	81	(pad same ((bond adhesive) same ((lead adj on adj chip) loc))) and ((257/676).CCLS.)	USPAT; US-PGPUB	2002/10/24 09:16
2	58	((pad same ((bond adhesive) same ((lead adj on adj chip) loc))) and ((257/666).CCLS.)) not ((pad same ((bond adhesive) same ((lead adj on adj chip) loc))) and ((257/676).CCLS.))	USPAT; US-PGPUB	2002/10/24 09:21
3	306	pad same ((bond adhesive) same ((lead adj over adj chip)))	USPAT; US-PGPUB	2002/10/24 09:32
4	58	(pad same ((bond adhesive) same ((lead adj over adj chip)))) not (pad same ((bond adhesive) same ((lead adj on adj chip) loc)))	USPAT; US-PGPUB	2002/10/24 09:28
5	30	pad same ((bond adhesive) same ((lead adj on adj chip) loc))	EPO; JPO; DERWENT; IBM_TDB	2002/10/24 09:29
6	14	pad same ((bond adhesive) same ((lead adj over adj chip)))	EPO; JPO; DERWENT; IBM_TDB	2002/10/24 09:30
7	0	standard same planar same (lead adj over adj chip)	USPAT; US-PGPUB	2002/10/24 09:32
8	4	standard same planar same (loc)	USPAT; US-PGPUB	2002/10/24 09:33